

# ULTRA PRECISION 8:1 MUX WITH INTERNAL TERMINATION AND 1:2 CML FANOUT BUFFER

Precision Edge<sup>®</sup> SY58037U

#### **FEATURES**

- Selects between 1 of 8 inputs, and provides two precision, low skew CML output copies
- Guaranteed AC performance over temperature and voltage:
  - DC to 5Gbps throughput
  - <450ps propagation delay IN-to-Q (V<sub>IN</sub> ≥ 300mV)
  - <70ps t<sub>r</sub> / t<sub>f</sub> time
  - <15ps skew (output-to-output)</li>
- Unique, patent-pending, channel-to-channel isolation design provides superior crosstalk performance
- Ultra-low jitter design:
  - <1ps<sub>RMS</sub> random jitter
  - <10ps<sub>pp</sub> deterministic jitter
  - <10ps<sub>pp</sub> total jitter (clock)
  - <0.7ps<sub>RMS</sub> crosstalk-induced jitter
- Unique, patent-pending, input termination and VT pin accepts DC- and AC-coupled inputs (CML, PECL, LVDS)
- 400mV CML output swing
- 50 $\Omega$  source terminated outputs minimize round-trip reflections
- Power supply 2.5V ±5% or 3.3V ±10%
- -40°C to +85°C temperature range
- Available in 44-pin (7mm x 7mm) QFN package

#### **APPLICATIONS**

- Data communication systems
- All SONET/SDH data/clock applications
- All Fibre Channel applications
- All Gigabit Ethernet applications



Precision Edge®

#### **DESCRIPTION**

The SY58037U is a low jitter, low skew, high-speed 8:1 multiplexer with a 1:2 differential fanout buffer optimized for precision telecom and enterprise server distribution applications. The SY58037U distributes clock frequencies from DC to 4GHz and data rates to 5Gpbs guaranteed over temperature and voltage.

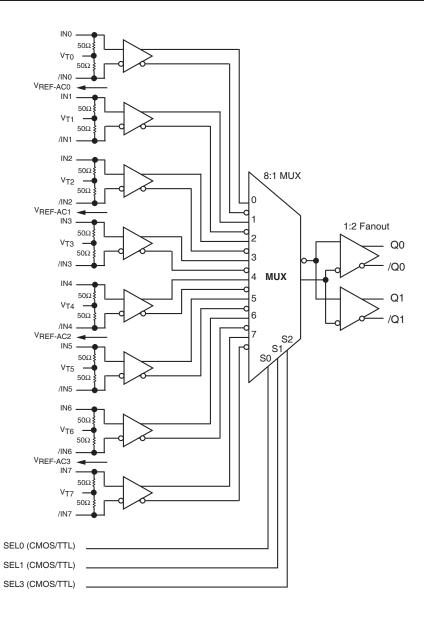
The SY58037U differential input includes Micrel's unique, 3-pin input termination architecture that directly interfaces to any differential signal (AC- or DC-coupled) as small as 100mV (200mVpp) without any level shifting or termination resistor networks in the signal path. The outputs are  $50\Omega$  source-terminated CML with extremely fast rise/fall time guaranteed to be less than 70ps.

The SY58037U features a patent-pending isolation design that significantly improves channel-to-channel crosstalk performance.

The SY58037U operates from a 2.5V  $\pm$ 5% or 3.3V  $\pm$ 10% supply and is guaranteed over the full industrial temperature range of  $-40^{\circ}$ C to  $+85^{\circ}$ C. The SY58037U is part of Micrel's high-speed, Precision Edge® product line.

Datasheets and support documentation can be found on Micrel's web site at www.micrel.com.

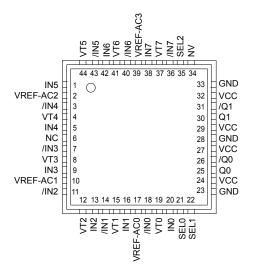
## **FUNCTIONAL BLOCK DIAGRAM**



## **TRUTH TABLE**

| SEL2 | SEL1 | SEL0 | Q   | /Q   |
|------|------|------|-----|------|
| L    | L    | L    | IN0 | /INO |
| L    | L    | Ι    | IN1 | /IN1 |
| L    | Н    | L    | IN2 | /IN2 |
| L    | Н    | Н    | IN3 | /IN3 |
| Н    | L    | L    | IN4 | /IN4 |
| Н    | L    | Н    | IN5 | /IN5 |
| Н    | Н    | L    | IN6 | /IN6 |
| Н    | Н    | Н    | IN7 | /IN7 |

## **PACKAGE/ORDERING INFORMATION**



Ordering Information<sup>(1)</sup>

| Part Number                 | Package<br>Type | Operating<br>Range | Package<br>Marking                       | Lead<br>Finish      |
|-----------------------------|-----------------|--------------------|--|---------------------|
| SY58037UMY                  | QFN-44          | Industrial         | SY58037U with Pb-Free bar-line indicator | Pb-Free<br>Matte-Sn |
| SY58037UMYTR <sup>(2)</sup> | QFN-44          | Industrial         | SY58037U with Pb-Free bar-line indicator | Pb-Free<br>Matte-Sn |

#### Notes:

- 1. Contact factory for die availability. Dice are guaranteed at  $T_A$  = 25°C, DC electricals only.
- 2. Tape and Reel.

44-Pin QFN

#### **PIN DESCRIPTION**

| Pin Number   | Pin Name   | Pin Function  |
|--|--|---|
| 20, 18,<br>16, 14,<br>13, 11,<br>9, 7,<br>5, 3,<br>1, 43,<br>42, 40,<br>38, 36 | IN0, /IN0,<br>IN1, /IN1,<br>IN2, /IN2,<br>IN3, /IN3,<br>IN4, /IN4,<br>IN5,/IN5,<br>IN6, /IN6,<br>IN7, /IN7 | Differential Inputs: These input pairs are the differential signal inputs to the device. Inputs accept AC or DC-coupled signals as small as 100mV. Each pin of a pair internally terminates to a VT pin through $50\Omega$ . Note that these inputs will default to an indeterminate state if left open. Please refer to the "Input Interface Applications" section for more details. |
| 19,15,<br>12, 8,<br>4, 44,<br>41, 37   | VT0, VT1<br>VT2, VT3,<br>VT4, VT5,<br>VT6, VT7   | Input Termination Center-Tap: Each side of the differential input pair terminates to a VT pin.  The VT pins provide a center-tap to a termination network for maximum interface flexibility.  See "Input Interface Applications" section for more details.  |
| 17,<br>10,<br>2<br>39  | VREF-AC0,<br>VREF-AC1,<br>VREF-AC2,<br>VREF-AC3  | Reference Voltage: This output biases to $V_{CC}$ –1.2V. It is used when AC coupling the inputs (IN, /IN). For AC-coupled applications, connect VREF_AC to the VT pin and bypass with a 0.01 $\mu$ F low ESR capacitor to $V_{CC}$ . See "Input Interface Applications" section for more details.   |
| 21,<br>22,<br>35   | SEL0,<br>SEL1,<br>SEL2   | The TTL/CMOS-compatible inputs select the inputs to the multiplexer. Note that this input is internally connected to a $25 \mathrm{k}\Omega$ pull-up resistor and will default to a logic HIGH state if left open.  |
| 24, 27, 29, 32   | VCC  | Positive Power Supply. Bypass with $0.1\mu F \mid 0.01\mu F$ low ESR capacitors as close to each VCC pin.   |
| 25, 26,<br>30, 31  | Q0,/Q0,<br>Q1,/Q1  | Differential Outputs: These CML output pairs are the outputs of the device. Please refer to the truth table below for details. Unused output pairs may be left open. Each output is designed to drive 400mV into 100Ω across each output pair.  |
| 23, 28, 33   | GND,<br>Exposed Pad  | Ground. GND and exposed pad must both be connected to the most negative potential of chip ground.   |

## **Absolute Maximum Ratings**(1)

| Power Supply Voltage (V <sub>CC</sub> )     | 0.5V to +4.0V            |
|---|--------------------------|
| Input Voltage (V <sub>IN</sub> )            | –0.5V to V <sub>CC</sub> |
| LVPECL Output Current (I <sub>OUT</sub> )   |                          |
| Continuous                                  | 50mA                     |
| Surge                                       | 100mA                    |
| Termination Current <sup>(3)</sup>          |                          |
| Source or sink current on VT pin            | ±100mA                   |
| Lead Temperature (soldering, 20 sec.)       | 260°C                    |
| Storage Temperature Range (T <sub>S</sub> ) | –65°C to +150°C          |

## Operating Ratings<sup>(2)</sup>

| Power Supply Voltage (V <sub>CC</sub> )     | . +2.375V to +2.625V |
|---|----------------------|
|   | +3.0V to +3.6V       |
| Ambient Temperature Range (T <sub>A</sub> ) | 40°C to +85°C        |
| Package Thermal Resistance <sup>(4)</sup>   |                      |
| QFN (θ <sub>JA</sub> )                      |                      |
| Still-Air                                   | 24°C/W               |
| QFN (ψ <sub>JB</sub> )                      |                      |
| Junction-to-board                           | 12°C/W               |

## DC ELECTRICAL CHARACTERISTICS(5)

 $T_A = -40$ °C to +85°C, unless otherwise stated.

| Symbol                  | Parameter                                    | Condition                       | Min                  | Тур                  | Max                  | Units |
|-------------------------|--|---------------------------------|----------------------|----------------------|----------------------|-------|
| $V_{CC}$                | Power Supply Voltage                         | V <sub>CC</sub> = 2.5V.         | 2.375                | 2.5                  | 2.625                | V     |
|                         |  | V <sub>CC</sub> = 3.3V.         | 3.0                  | 3.3                  | 3.6                  | V     |
| I <sub>CC</sub>         | Power Supply Current                         | No load, max. V <sub>CC</sub> . |                      | 145                  | 200                  | mA    |
| R <sub>IN</sub>         | Input Resistance (IN-to-V <sub>T</sub> )     |                                 | 40                   | 50                   | 60                   | Ω     |
| R <sub>DIFF_IN</sub>    | Differential Input Resistance (IN-to-/IN)    |                                 | 80                   | 100                  | 120                  | Ω     |
| V <sub>IH</sub>         | Input HIGH Voltage<br>(IN-to-/IN)            |                                 | V <sub>CC</sub> -1.2 |                      | V <sub>CC</sub>      | V     |
| V <sub>IL</sub>         | Input LOW Voltage<br>(IN-to-/IN)             |                                 | 0                    |                      | V <sub>IH</sub> -0.1 | V     |
| V <sub>IN</sub>         | Input Voltage Swing (IN-to-/IN)              | See Figure 1a.                  | 0.1                  |                      | 1.7                  | V     |
| V <sub>DIFF_IN</sub>    | Differential Input Voltage Swing (IN-to-/IN) | See Figure 1b.                  | 0.2                  |                      |                      | V     |
| $\overline{V_{T_{IN}}}$ | IN to V <sub>T</sub> (IN-to-/IN)             |                                 |                      |                      | 1.28                 | V     |
| V <sub>REF-AC</sub>     | Output Reference Voltage                     |                                 | V <sub>CC</sub> -1.3 | V <sub>CC</sub> -1.2 | V <sub>CC</sub> -1.1 | V     |

#### Notes:

- 1. Permanent device damage may occur if ratings in the "Absolute Maximum Ratings" section are exceeded. This is a stress rating only and functional operation is not implied for conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- 3. Due to the limited drive capability, use for input of the same package only.
- 4. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB.  $\Psi_{JB}$  uses 4-layer  $\theta_{JA}$  in still-air number unless otherwise stated.
- 5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

## CML OUTPUT DC ELECTRICAL CHARACTERISTICS<sup>(7)</sup>

 $V_{CC}$  = 2.5V ±5% or 3.3V ±10%;  $T_A$  = -40°C to +85°C;  $R_L$  = 100 $\Omega$  across each output pair, unless otherwise stated.

| Symbol                | Parameter                               | Condition      | Min                    | Тур                    | Max             | Units |
|-----------------------|---|----------------|------------------------|------------------------|-----------------|-------|
| V <sub>OH</sub>       | Output HIGH Voltage<br>Q, /Q            |                | V <sub>CC</sub> -0.040 | V <sub>CC</sub> -0.010 | V <sub>CC</sub> | V     |
| V <sub>OUT</sub>      | Output Differential Swing Q, /Q         | See Figure 1a. | 325                    | 400                    |                 | mV    |
| V <sub>DIFF_OUT</sub> | Differential Output Voltage Swing Q, /Q | See Figure 1b. | 650                    | 800                    |                 | mV    |
| R <sub>OUT</sub>      | Output Source Impedance                 |                | 40                     | 50                     | 60              | Ω     |

#### LVTTL/CMOS DC ELECTRICAL CHARACTERISTICS<sup>(7)</sup>

 $V_{CC}$  = 2.5V  $\pm 5\%$  or 3.3V  $\pm 10\%;$   $T_A = -40^{\circ}C$  to +85°C, unless otherwise stated.

| Symbol          | Parameter          | Condition | Min  | Тур | Max             | Units |
|-----------------|--------------------|-----------|------|-----|-----------------|-------|
| $V_{IH}$        | Input HIGH Voltage |           | 2.0  |     | V <sub>CC</sub> | V     |
| $V_{IL}$        | Input LOW Voltage  |           |      |     | 0.8             | V     |
| I <sub>IH</sub> | Input HIGH Current |           | -125 |     | 30              | μА    |
| I <sub>IL</sub> | Input LOW Current  |           | -300 |     |                 | μΑ    |

#### Note:

7. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

## AC ELECTRICAL CHARACTERISTICS(8)

 $V_{CC}$  = 2.5V ±5% or 3.3V ±10%;  $T_A$  = -40°C to +85°C,  $R_L$  = 100 $\Omega$  across each output pair or equivalent, unless otherwise stated.

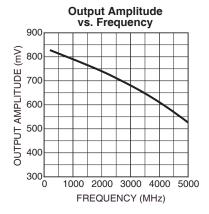
| Symbol                          | Paramete  | r  | Condition                         | Min    | Тур   | Max     | Units                                 |
|---------------------------------|---|--|-----------------------------------|--------|-------|---------|---------------------------------------|
| f <sub>MAX</sub>                | Maximum Operating Frequency                                 |  | NRZ data<br>Clock                 | 5<br>4 |       |         | Gbps<br>GHz                           |
| t <sub>pd</sub>                 | Differentia   | I Propagation Delay (IN-to-Q)              | $V_{IN} \ge 100 mV$               | 240    | 35550 | 450     | ps                                    |
|                                 |   | (SEL-to-Q)                                 |                                   | 100    |       | 550     | ps                                    |
| ∆t <sub>pd</sub> Tempco         | o Differential Propagation Delay<br>Temperature Coefficient |  |                                   |        | 215   |         | fs/°C                                 |
| t <sub>SKEW</sub>               |   | Output-to-Output Skew                      | Note 9                            |        |       | 15      | ps                                    |
|                                 |   | Part-to-Part Skew                          | Note 10                           |        |       | 150     | ps                                    |
| t <sub>JITTER</sub>             | Data  | Random Jitter (RJ)                         | Note 11                           |        |       | 1       | ps <sub>RMS</sub>                     |
|                                 |   | Deterministic Jitter (DJ)                  | Note 12                           |        |       | 10      | ps <sub>PP</sub>                      |
|                                 | Clock   | Cycle-to-Cycle Jitter<br>Total Jitter (TJ) | Note 13<br>Note 14                |        |       | 1<br>10 | ps <sub>RMS</sub><br>ps <sub>PP</sub> |
|                                 |   | Crosstalk-induced Jitter                   | Note 15                           |        |       | 0.7     | ps <sub>RMS</sub>                     |
| t <sub>r</sub> , t <sub>f</sub> | Output Rise/Fall Time                                       |  | At full output swing, 20% to 80%. | 20     | 40    | 70      | ps                                    |

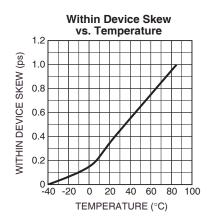
#### Notes:

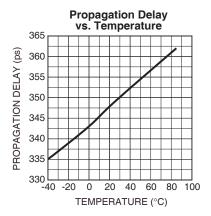
- 8. High-frequency AC-parameters are guaranteed by design and characterization.
- 9. Output-to-output skew is measured between two different outputs under identical input transitions.
- 10. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs
- 11. Random jitter is measured with a K28.7 character pattern, measured at  $\leq f_{MAX}$ .
- 12. Deterministic jitter is measured at 2.5Gbps/3.2Gbps, with both K28.5 and 2<sup>23</sup>–1 PRBS pattern.
- 13. Cycle-to-cycle jitter definition: the variation of periods between adjacent cycles,  $T_n T_{n-1}$  where T is the time between rising edges of the output signal.
- 14. Total jitter definition: with an ideal clock input of frequency ≤f<sub>MAX</sub>, no more than one output edge in 10<sup>12</sup> output edges will deviate by more than the specified peak-to-peak jitter value.
- 15. Crosstalk is measured at the output while applying two similar differential clock frequencies that are asynchronous with respect to each other adjacent inputs.

## **TYPICAL OPERATING CHARACTERISTICS**

 $V_{CC}$  = 3.3V, GND = 0,  $V_{IN}$  = 100mV,  $T_A$  = 25°C, unless otherwise stated.

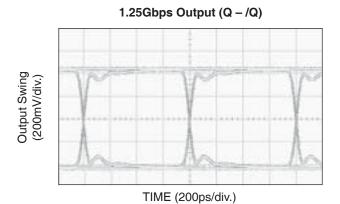


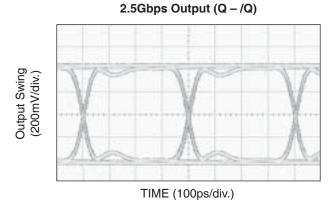




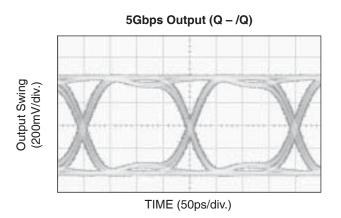
## **FUNCTIONAL CHARACTERISTICS**

 $\rm V_{CC}$  = 3.3V, GND = 0,  $\rm V_{IN}$  = 100mV,  $\rm T_A$  = 25°C, unless otherwise stated.





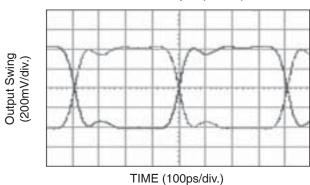




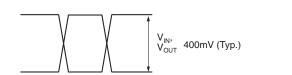
Outbut Swing (200mV/div.)

TIME (600ps/div.)

622MHz Output (Q – /Q)



## SINGLE-ENDED AND DIFFERENTIAL SWINGS





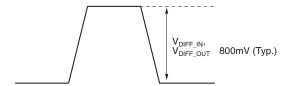


Figure 1b. Differential Voltage Swing

#### **INPUT AND OUTPUT STAGES**

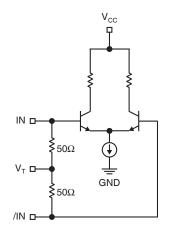


Figure 2a. Simplified Differential Input Stage

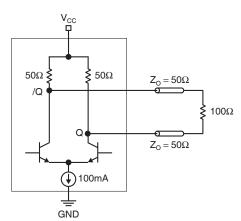


Figure 2b. CML DC-Coupled (100 $\Omega$  Termination)

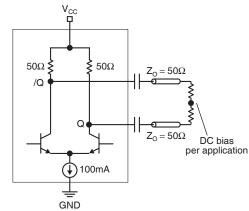


Figure 2c. CML AC-Coupled (50 $\Omega$  Termination)

## **INPUT INTERFACE APPLICATIONS**

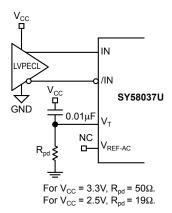


Figure 3a. LVPECL Interface (DC-Coupled)

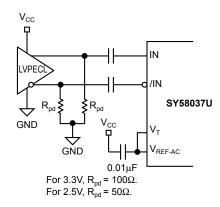
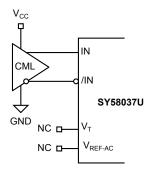


Figure 3b. LVPECL Interface (AC-Coupled)



Option: May connect  $V_T$  to  $V_{CC}$ .

Figure 3c. CML Interface (DC-Coupled)

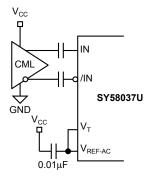


Figure 3d. CML Interface (AC-Coupled)

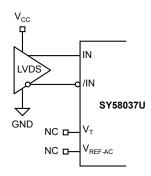
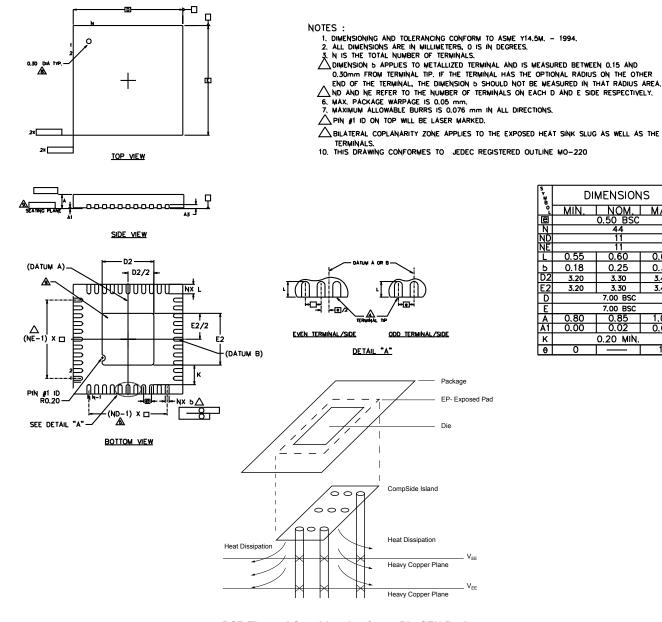


Figure 3e. LVDS Interface

#### RELATED MICREL PRODUCTS AND SUPPORT DOCUMENTATION

| Part Number   | Function   | Data Sheet Link  |
|---------------|--|--|
| SY58037U      | Ultra Precision 8:1 MUX with Internal Termination and 1:2 CML Fanout Buffer          | http://www.micrel.com/product-info/products/sy58037u.shtml |
| SY58038U      | Ultra Precision 8:1 MUX with Internal Termination and 1:2 LVPECL Fanout Buffer       | http://www.micrel.com/product-info/products/sy58038u.shtml |
| SY58039U      | Ultra Precision 8:1 MUX with Internal Termination and 1:2 400mV LVPECL Fanout Buffer | http://www.micrel.com/product-info/products/sy58039u.shtml |
| HBW Solutions | New Products and Applications  | www.micrel.com/product-info/products/solutions.shtml       |

#### 44-PIN QFN (QFN-44)



DIMENSIONS NOM 0.65 0,60 0.30 0.18 0.25 3,30 3,40 3,30 7.00 BS 7.00 BSC 0.20 MIN

PCB Thermal Consideration for 44-Pin QFN Package (Always solder, or equivalent, the exposed pad to the PCB)

#### **Package Notes:**

- 1. Package meets Level 2 qualification.
- 2. All parts are dry-packaged before shipment.
- 3. Exposed pads must be soldered to a ground for proper thermal management.

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